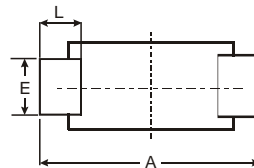
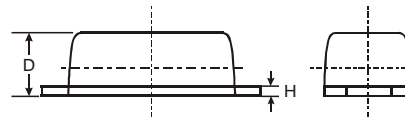
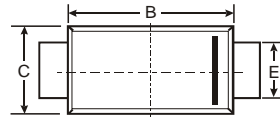
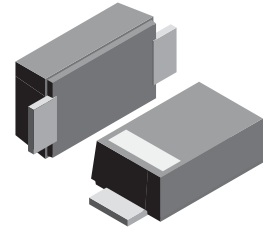


VOLTAGE RANGE: 50 - 1000V
CURRENT: 3.0 A

Features

- Glass Passivated Die Construction
- Ideally Suited for Automatic Assembly
- Low Forward Voltage Drop, High Efficiency
- Low Power Loss
- Ultra-Fast Recovery Time
- Plastic Case Material has UL Flammability Classification Rating 94V-O



SMAF			
Dim	Min	Max	Typ
A	4.75	4.85	4.80
B	3.68	3.72	3.70
C	2.57	2.63	2.60
D	0.097	1.03	1.00
E	1.38	1.42	1.40
H	0.13	0.17	0.15
L	0.63	0.67	0.65
All Dimensions in mm			

Mechanical Data

- Case: SMAF, Molded Plastic
- Terminals: Solder Plated, Solderable per MIL-STD-750, Method 2026
- Polarity: Color band denotes cathode end
- Mounting Position: Any
- Weight: 0.0018 ounce, 0.064 grams



Maximum Ratings and Electrical Characteristics T_A = 25°C unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

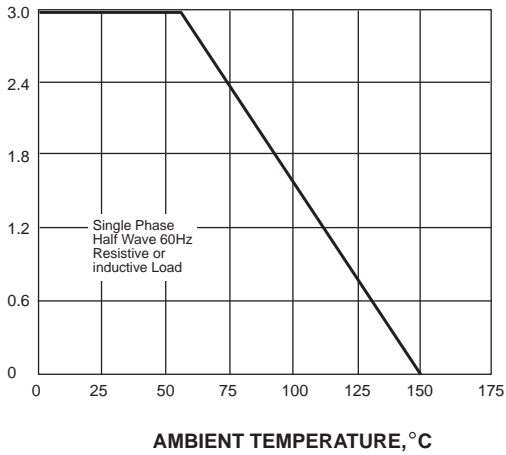
Characteristic	Symbol	US3AAF	US3BAF	US3DAF	US3GAF	US3JAF	US3KAF	US3MAF	Unit	
Maximum repetitive peak reverse voltage	V _{RRM}	50	100	200	400	600	800	1000	V	
Maximum RMS voltage	V _{RMS}	35	70	140	280	420	560	700	V	
Maximum DC blocking voltage	V _{DC}	50	100	200	400	600	800	1000	V	
Maximum average forward rectified current 0.375" (9.5mm) lead length at T _A =55°C	I _(AV)	3.0							A	
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}	100.0							A	
Maximum instantaneous forward voltage at 3.0A	V _F	1.0		1.30		1.70			V	
Maximum DC reverse current T _A =25°C at rated DC blocking voltage T _A =100°C	I _R	5.0 250.0							μA	
Maximum reverse recovery time (NOTE 1)	t _{rr}	50				75				ns
Typical junction capacitance (NOTE 2)	C _J	75							pF	
Typical thermal resistance (NOTE 3)	R _{θJL}	15.0							°C/W	
Operating junction and storage temperature range	T _J , T _{STG}	-65 to +150							°C	

- Note:** 1. Reverse recovery condition I_F=0.5A, I_R=1.0A, I_{rr}=0.25A
 2. Measured at 1MHz and applied reverse voltage of 4.0V D.C.
 3. Thermal resistance from junction to lead and from junction to ambient with P.C.B mounted on 0.3 x 0.3" (8.0 x 8.0 mm) Copper pad area

RATINGS AND CHARACTERISTIC CURVES US3AAF THRU US3MAF

AVERAGE FORWARD RECTIFIED CURRENT, AMPERES

FIG. 1- FORWARD CURRENT DERATING CURVE



PEAK FORWARD SURGE CURRENT, AMPERES

FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

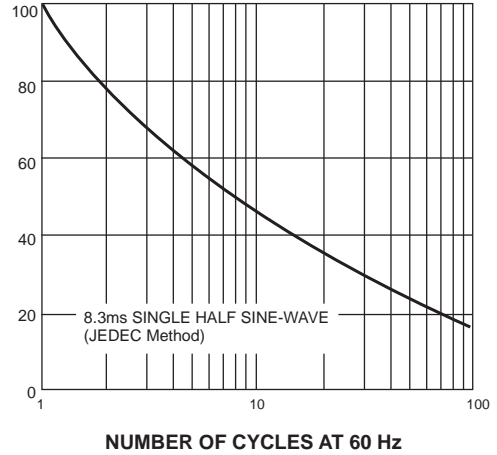
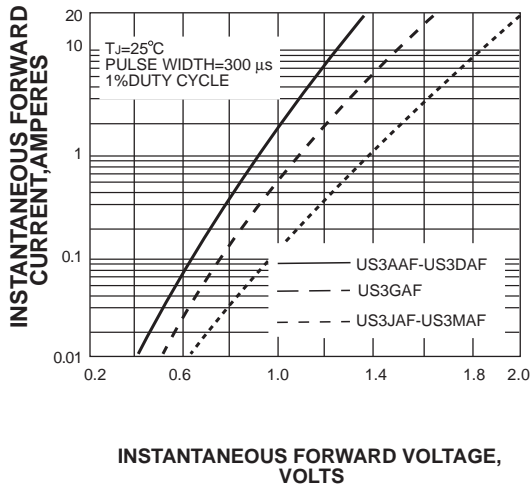
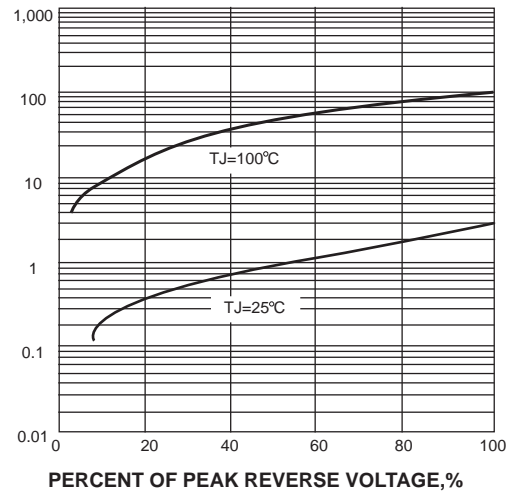


FIG. 3-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS



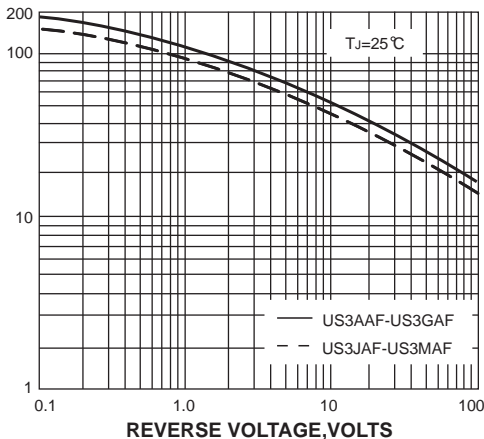
INSTANTANEOUS REVERSE CURRENT, MICROAMPERES

FIG. 4-TYPICAL REVERSE CHARACTERISTICS



JUNCTION CAPACITANCE, pF

FIG. 5-TYPICAL JUNCTION CAPACITANCE



TRANSIENT THERMAL IMPEDANCE, °C/W

FIG. 6-TYPICAL TRANSIENT THERMAL IMPEDANCE

